REMARKS

The Applicants request reconsideration of the rejection.

Claims 1-16 remain pending.

The specification has been amended to address the informality noted on Page 2 of the Office Action.

Claims 13-16 were rejected under 35 U.S.C. §102(e) as being anticipated by Ito, U.S. 6,703,261 (Ito). The Applicants traverse as follows.

As originally filed, Claim 13 was directed to a semiconductor device comprising a metal plate, a plurality of leads connected electrically to a semiconductor chip mounted on the metal plate, and a molding body for molding a chip and a part of each of the leads, wherein each lead has one end disposed above a depressed portion of the metal plate. Thus, Claim 13 was patentably distinguishable over Ito in view of the requirement that each of the leads have one end disposed above a depressed portion of the metal plate.

In rejecting the claim, the Examiner referred to metal plate ("screwing piece") 4 having an edge portion formed with a depressed portion ("screwing piece") 4a. It is not clear whether the rejection relies on screwing piece 4a as corresponding to the claimed edge portion or the claimed depressed portion.

Nevertheless, screwing piece 4a represents screwing piece 4a in the lead frame stage 40 shown in Fig. 8 of the patent. The patent does not show the screwing piece to have a depressed portion at an edge portion thereof. Moreover, the original claims requires the metal plate to mount the semiconductor chip and therefore the plate mounting semiconductor chip to have the depressed portion. In Ito, however, the screwing portion 4 does not mount the semiconductor chip.

Claim 13 has been amended to emphasize this feature of the invention. Now, amended Claim 13 requires that each lead be comprised of an inner and outer lead portion, the inner lead portion be positioned inside the molding body and the outer lead portion be positioned outside the molding body, the depressed portion of the metal plate be positioned inside the molding body, and the inner lead portion be positioned over the depressed portion of the metal plate. This structure clearly distinguishes Ito, in which the semiconductor chip 15 is mounted on the heat sink 3 and not the screwing piece 4, as noted above (and the screwing piece 4 (4a) is not depressed from the heat sink 3, and leads 5,6 are not positioned over the heat sink 3 or the screwing piece 4 (4a).

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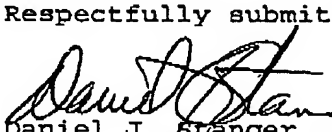
In view of the foregoing amendments and remarks, the Applicants request reconsideration of the rejection and allowance of the claims.

Respectfully submitted,



Daniel J. Stanger
Registration No. 32,846
Attorney for Applicants

MATTINGLY, STANGER, MALUR & BRUNDIDGE, P.C.
1800 Diagonal Rd., Suite 370
Alexandria, Virginia 22314
(703) 684-1120
Date: May 23, 2005